

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Whonchee Lee, Scott G. Meikle, Scott E. Moore
Filed : Concurrently herewith
For : MICROELECTRONIC SUBSTRATE HAVING
CONDUCTIVE MATERIAL WITH BLUNT CORNERED
APERTURES, AND ASSOCIATED METHODS FOR
REMOVING CONDUCTIVE MATERIAL

Docket No. : 108298515US2

Box Patent Application
Commissioner for Patents
Washington, DC 20231

ELECTION UNDER 37 C.F.R. §§ 3.71 AND 3.73 AND POWER OF
ATTORNEY

Sir:

The undersigned, being Assignee of the entire interest in the above-identified application by virtue of an Assignment filed concurrently herewith, hereby elects, under 37 C.F.R. § 3.71, to prosecute the application to the exclusion of the inventor.

Assignee hereby appoints JERRY A. RIEDINGER, Registration No. 30,582; MAURICE J. PIRIO, Registration No. 33,273; MICHAEL D. BROADDUS, Registration No. 41,637; CATHERINE HONG TRAN, Registration No. 43,960; ROBERT G. WOOLSTON, Registration No. 37,263; PAUL T. PARKER, Registration No. 38,264; JOHN M. WECHKIN, Registration No. 42,216; CHRISTOPHER DALEY-WATSON, Registration No. 34,807; STEVEN D. LAWRENZ, Registration No. 37,376; JAMES A.D. WHITE, Registration No. 43,985; EDWARD S. HOTCHKISS, Registration No. 33,904; JAMES NICKELSON,

Registration No. 46,140; STEPHEN E. ARNETT, Registration No. 47,392; and DAVINA L. CHILDS, Registration No. 47,485, all attorneys with the firm Perkins Coie LLP, along with MICHAEL L. LYNCH, Reg. No. 30,871; CHARLES B. BRANTLEY, II, Reg. No. 38,086; KEVIN D. MARTIN, Reg. No. 37,882; and DAVID J. PAUL, Reg. No. 34,692, of Micron Technology, Inc., 8000 South Federal Way, Boise, Idaho 83706-9632 as the principal attorneys with full power of substitution, association, and revocation to prosecute said application, to transact all business in the Patent and Trademark Office connected therewith, and to receive the letters patent therefor. Please direct all direct all telephone calls to John M. Wechkin at (206) 583-8888 and telecopies to (206) 583-8500.

Please direct all communications to:

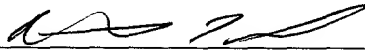
Patent-SEA
Perkins Coie LLP
P. O. Box 1247
Seattle, Washington 98111-1247
Attn: John M. Wechkin

Pursuant to 37 C.F.R. § 3.73, the undersigned duly authorized designee of Assignee certifies that the evidentiary documents have been reviewed, specifically the Assignment to MICRON TECHNOLOGY, INC., filed concurrently herewith for recording, a copy of which is attached hereto, and certifies that to the best of my knowledge and belief, title remains in the name of the Assignee.

MICRON TECHNOLOGY, INC.

DATE

6-7-01


Michael L. Lynch
Chief Patent Counsel

Enclosure:

Copy of Assignment

DECLARATION

As the below-named inventors, we declare that:

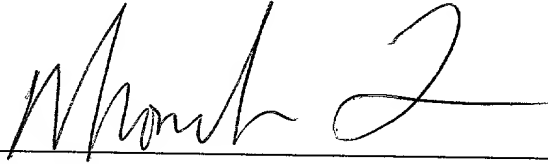
Our residences, post office addresses, and citizenships are as stated below under our names.

We believe we are the original, first, and joint inventors of the subject matter claimed and for which a patent is sought on the invention entitled "MICROELECTRONIC SUBSTRATE HAVING CONDUCTIVE MATERIAL WITH BLUNT CORNERED APERTURES, AND ASSOCIATED METHODS FOR REMOVING CONDUCTIVE MATERIAL," as filed in the foregoing specification, and this application is a continuation-in-part of U.S. Application No. 09/651,779 (attorney docket number 108298515US), titled "Methods and Apparatus for Removing Conductive Material From a Microelectronic Substrate," filed August 30, 2000, and U.S. Application No. _____ (attorney docket number 108298515US1), titled "Methods and Apparatus for Electrical, Mechanical and/or Chemical Removal of Conductive Material from a Microelectronic Substrate," filed concurrently herewith, and U.S. Application No. _____ (attorney docket number 108298515US3), titled "Methods and Apparatus for Electrically and/or Chemically-Mechanically Removing Conductive Material From a Microelectronic Substrate," filed concurrently herewith, all of which are incorporated herein in their entireties by reference.

We have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment specifically referred to above.

We acknowledge our duty to disclose information of which is material to the patentability of this application in accordance with 37 C.F.R. § 1.56(a), including material information which became available between the filing date of the prior application and the filing date of the present application.

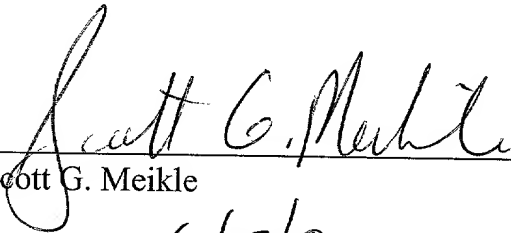
We further declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that the making of willfully false statements and the like is punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and may jeopardize the validity of any patent issuing from this patent application.



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